

EVA[VS430]

- **Attributes :** Processability, Mechanical Properties, Bead Foaming Properties
- **Applications :** SHOE SOLE, Electric Wire BASE RESIN (inner semiconductive layer)
- **Certification :** -

- **Properties DATA SHEET**

Properties	Test Method	Unit	Properties
Melt Flow Rate(MFR)	D1238	g/10min	2.5
VA Content	HPC	wt. %	19
Density	D1505	g/cm ³	0.939
Melting Point	HPC	°C	84
Softening Point	D1525	°C	64
Tensing Strength at Break	D1238	g/10min	140
Ultimate Elongation	HPC	wt. %	670
Hardness (Rockwell)	D1505	g/cm ²	38
Tensile Modulus	HPC	°C	300
Electrical Permittivity	D1531	-	-
Electrical Volume Resistivity	D257	Ω·cm	-

Above data are not the spec. of products, but only for reference.